

AMPMODU | AMPMODU HE 13/HE 14

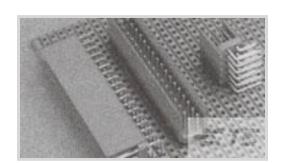
TE Internal #: 281739-6

PCB Mount Header, Vertical, Wire-to-Board, 12 Position, 2.54 mm [. 1 in] Centerline, Partially Shrouded, Tin, AMPMODU HE 13/HE 14

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Connectors > PCB Connectors > PCB Headers & Receptacles > HE13/HE14 TH Headers, DRST



Connector System: Wire-to-Board

Number of Positions: 12

Number of Rows: 2

Centerline (Pitch): 2.54 mm [.1 in]
PCB Mount Orientation: Vertical

All HE13/HE14 TH Headers, DRST (20)

Features

Product Type Features

| Connector System | Wire-to-Board |
|-----------------------------------|-----------------------|
| Header Type | Partially Shrouded |
| Sealable | No |
| Connector & Contact Terminates To | Printed Circuit Board |
| PCB Connector Assembly Type | PCB Mount Header |

Configuration Features

| Connector Contact Load Condition | Fully Loaded |
|----------------------------------|--------------|
| Number of Positions | 12 |
| Number of Rows | 2 |
| PCB Mount Orientation | Vertical |

Electrical Characteristics

| Insulation Resistance | 1000 ΜΩ |
|---------------------------------------|---------|
| Dielectric Withstanding Voltage (Max) | 500 V |

Body Features

| Primary Product Color | Blue | |
|-----------------------|------|--|
|-----------------------|------|--|

Contact Features

| Cor | ntact Mating Area Length | 7 mm | |
|-----|--------------------------|------|--|
| | | | |



| Mating Square Post Dimension | .64 mm[.025 in] |
|--|--------------------------------|
| Contact Mating Area Plating Material Thickness | .8 μm[31 μin] |
| Contact Shape & Form | Square |
| Contact Mating Area Plating Material Finish | Matte |
| Contact Underplating Material | Nickel |
| PCB Contact Termination Area Plating Material | Tin |
| Contact Base Material | Phosphor Bronze |
| Contact Mating Area Plating Material | Tin |
| Contact Type | Pin |
| Contact Current Rating (Max) | 3 A |
| Termination Features | |
| Square Termination Post & Tail Dimension | .63 mm[.025 in] |
| Termination Post & Tail Length | 2.9 mm |
| Termination Method to Printed Circuit Board | Through Hole - Solder |
| Mechanical Attachment | |
| Mating Alignment Type | Polarization |
| Mating Retention | With |
| Panel Mount Feature | Without |
| Connector Mounting Type | Board Mount |
| Mating Alignment | With |
| PCB Mount Retention | Without |
| Housing Features | |
| Housing Material | High Temperature Thermoplastic |
| Centerline (Pitch) | 2.54 mm[.1 in] |
| Dimensions | |
| Row-to-Row Spacing | 2.54 mm[.1 in] |
| Usage Conditions | |
| Operating Temperature Range | -40 - 100 °C[-40 - 212 °F] |
| | |
| Operation/Application | |
| Operation/Application Circuit Application | Signal |
| | Signal |



Packaging Features

| Packaging Quantity | 2000 |
|--------------------|------|
| Packaging Type | Box |

Product Compliance

For compliance documentation, visit the product page on TE.com>

| EU RoHS Directive 2011/65/EU | Compliant |
|---|---|
| EU ELV Directive 2000/53/EC | Compliant |
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold |
| EU REACH Regulation (EC) No. 1907/2006 | Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235) Does not contain REACH SVHC |
| Halogen Content | Not Low Halogen - contains Br or Cl > 900 ppm. |
| Solder Process Capability | Wave solder capable to 265°C |

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts





Also in the Series | AMPMODU HE 13/HE 14





Insertion & Extraction Tools(1)



PCB Headers & Receptacles(83)



Wire-to-Board Connector Assemblies & Housings(131)



Customers Also Bought



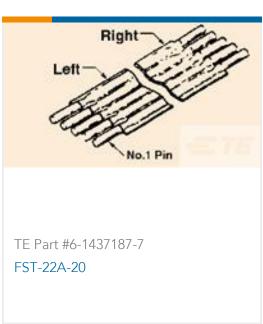












Documents

Product Drawings

HEADER HE14 STRAIGHT 2X6 P

English

CAD Files

Customer View Model

ENG_CVM_CVM_281739-6_G.2d_dxf.zip

English

3D PDF

3D

Customer View Model

ENG_CVM_CVM_281739-6_G.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_281739-6_G.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

PCB Mount Header, Vertical, Wire-to-Board, 12 Position, 2.54 mm [.1 in] Centerline, Partially Shrouded, Tin, AMPMODU HE 13/HE 14



Product Specifications
Product Specification

French